

ABSTRACT OF THE DISCLOSURE

PAD-TEMPERATURE REGULATING APPARATUS, PAD-TEMPERATURE REGULATING METHOD, 5 AND POLISHING APPARATUS

A pad-temperature regulating device is disclosed, which can improve a responsiveness of a control for a surface temperature of a polishing pad and regulate the surface temperature of the polishing pad without causing defects, such as scratches, on the substrate. The pad-temperature regulating apparatus includes: a heat exchanger disposed
10 above the polishing pad, whose temperature is maintained at a predetermined temperature; a pad-temperature measuring device configured to measure the surface temperature of the polishing pad; a distance sensor configured to measure a separation distance between the polishing pad and the heat exchanger; an elevating mechanism for moving the heat
15 exchanger vertically with respect to the polishing pad; and a controller configured to control operation of the elevating mechanism based on measured values of the pad-temperature measuring device.

FIG. 1

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